

WHAT IS CLAIMED IS:

1. A method for detecting defects in a material, comprising:
obtaining an image of at least a portion of a material's
surface;
converting the image into an intensity profile; and
determining a defect in the material's surface from the
intensity profile.

2. The method as recited in Claim 1 wherein obtaining an
image includes obtaining an electron image.

3. The method as recited in Claim 2 wherein obtaining an
electron image includes obtaining an electron image using a
scanning electron microscope.

4. The method as recited in Claim 1 further including
selecting an intensity line profile from the intensity profile.

5. The method as recited in Claim 4 wherein determining a
defect in the material's surface from the intensity profile
includes determining a defect in the material's surface from the
intensity line profile.

6. The method as recited in Claim 5 further including
2 selecting a plurality of intensity line profiles from the intensity
3 profile and determining a defect in each of the plurality of
4 intensity line profiles.

7. The method as recited in Claim 1 further including
2 selecting a plurality of intensity line profiles from the intensity
3 profile and determining a defect density of the plurality of
4 intensity line profiles.

8. The method as recited in Claim 1 wherein determining a
2 defect of the material's surface includes determining a total
3 number of intensity pixels.

9. The method as recited in Claim 8 wherein determining a
2 total number of intensity pixels includes determining a number of
3 background intensity pixels and a number of defect intensity
4 pixels.

10. The method as recited in Claim 9 further including
2 determining a defect density by dividing the number of defect
3 intensity pixels by the total number of intensity pixels.

11. The method as recited in Claim 9 wherein the total number
2 of intensity pixels comprise a histogram and the background
3 intensity pixels are inside a desired sigma value and the defect
4 intensity pixels are outside the desired sigma value.

12. The method as recited in Claim 11 wherein the desired
2 sigma value is greater than about 2 sigma.

13. The method as recited in Claim 12 wherein the desired
sigma value is greater than about 4 sigma.

14. The method as recited in Claim 10 wherein the intensity
2 profile includes a plurality of pixels and determining a defect of
3 the material's surface further includes determining an average
4 intensity of the plurality of pixels or determining a standard
5 deviation of the intensity profile.

15. The method as recited in Claim 10 wherein the number of
2 defect intensity pixels does not include the number of defect
3 intensity pixels having an intensity greater than an average
4 intensity.

16. The method as recited in Claim 1 wherein obtaining an
image of at least a portion of a material's surface includes
obtaining an image of an inner surface of a tubing located in a
semiconductor wafer manufacturing facility.

17. A system for detecting defects in a material, comprising:
a first subsystem that obtains an image of at least a portion
of a material's surface; and
a second subsystem that converts the image into an intensity
profile and determines a defect in the material's surface from the
intensity profile.

18. The system as recited in Claim 17 wherein the first
subsystem includes a scanning electron microscope that obtains an
electron image.

19. The system as recited in Claim 17 wherein the second
subsystem includes a computer subsystem including an operator
interface.

20. The system as recited in Claim 17 wherein the second
subsystem selects an intensity line profile from the intensity
profile.

21. The system as recited in Claim 20 wherein the second
subsystem determines a defect in the material's surface from the
intensity line profile.

22. The system as recited in Claim 17 wherein the second
2 subsystem determines a total number of intensity pixels.

23. The system as recited in Claim 22 wherein the total
2 number of intensity pixels includes a number of background
3 intensity pixels and a number of defect intensity pixels.

24. The system as recited in Claim 23 wherein the second
2 subsystem further determines a defect density by dividing the
number of defect intensity pixels by the total number of intensity
pixels.

25. The system as recited in Claim 23 wherein the total
number of intensity pixels comprise a histogram and the background
intensity pixels are inside a desired sigma value and the defect
intensity pixels are outside the desired sigma value.

26. The system as recited in Claim 25 wherein the desired
2 sigma value is greater than about 2 sigma.

27. The system as recited in Claim 26 wherein the desired
2 sigma value is greater than about 4 sigma.

28. The system as recited in Claim 17 wherein the material is
2 a tubing located in a semiconductor wafer manufacturing facility.

29. A method of using a system for detecting defects in a material, comprising:

detecting defects in a material, including;
obtaining an image of the material's surface;
converting the image into an intensity profile; and
determining defects in the material's surface from the intensity profile;
rejecting the material based upon a number of the defects in the material's surface.

30. The method as recited in Claim 29 wherein the material is a subset of a batch of the material and rejecting includes rejecting the batch of the material.